

ITS3

#### Tuesday 17<sup>th</sup> January 2023

# WP5 bi-weekly meeting

#### M.Angeletti

on behalf of WP5

# Outline

- Alternative h-ring design
- Next Engineer/Breadboard models
- Alternatives (R.Barthel)







# Alternative h-ring design

## • <u>Under consideration</u>: H-ring with L-cross-section



# H-detector BP H-L0 H-L1 H-L2 CYSS

## Advantages

 Increase thermal efficiency (H-L1, H-L2)

#### Disadvantages

- Manufacturing complexity
- Assembly complexity

#### NO INCREASE of thermal efficiency H-LO

Under consideration

### Model1:

- Objective: <u>real sensor integration</u> (bending, wire-bonds)
- Only one layer (H-LO)
- Ingredients:
  - Sensor: <u>Central piece MLR1 (H-L0 size</u>) (availability? @Magnus)
  - FPC + wire-bonds: FPC in production, mid February (@Antoine)



- Objective: <u>Assembly of 3 (dummy) sensors wire-bonded to FPCs</u>
- 3 layers
- Ingredients:
  - Sensor: <u>Dummy silicon</u> (coating availability?@Miranda/Thomas)
  - FPC + wire-bonds: H-L1 H-L2 FPC to be designed (@Antoine)







<u>Under consideration</u>

Model3 :

- Objective: Assembly of 3 (dummy) sensors wire-bonded to FPCs (both A- and C-side)
- 3 layers
- Ingredients:
  - Sensor: Dummy silicon
  - FPC + wire-bonds: C-Side FPC design to be defined (inputs from @Antoine and @Gianluca)



ALICE ITS3 WP

## Alternatives (R.Barthel): Next

ALICE ITS3 WP5

## Carbon fiber longerons and rings



- Possible test?
  - 3point bending test....
  - Compression test...
- Possible integration on a BM\EMs ?
  - Tools for the assembly at Utrecht?
  - Barthel availability to come at CERN? Or Dummy silicon shipment to Utrecht?
  - Convex/concave mandrel?
  - Self-supporting layers?







 Possible integration on a BM\EMs ?



Self-supporting layer configuration? Concave mandrel?

